

### Features

- Ultra-Small Surface Mount Package
- Guard Ring Die Construction for Transient Protection
- High Surge Capability
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

### Mechanical Data

- Case: POWERDI323
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Polarity: Cathode Band
- Terminals: Finish - Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 (e3)
- Weight: 0.006 grams (approximate)

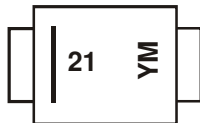


### Ordering Information (Note 4)

Part Number	Case	Packaging
PD3S230L-7	POWERDI323	3000/Tape & Reel
PD3S230LQ-7	POWERDI323	3000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
  2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com>.

### Marking Information



21 = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: W = 2009)  
 M = Month (ex: 9 = September)

#### Date Code Key

Year	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018
Code	W	X	Y	Z	A	B	C	D	E	F

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	30	V
Working Peak Reverse Voltage	$V_{RWM}$		
DC Blocking Voltage	$V_R$		
Average Forward Current (See also figure 4)	$I_{F(AV)}$	2.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	$I_{FSM}$	30	A

**Thermal Characteristics**

Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance Junction to Soldering Point	$R_{\theta JS}$	—	6.0	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction to Ambient Air (Note 5) $T_A = +25^\circ\text{C}$	$R_{\theta JA}$	177	—	$^\circ\text{C}/\text{W}$
Operating Temperature Range	$T_J$	-65 to +125		$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-65 to +150		$^\circ\text{C}$

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	30	—	—	V	$I_R = 1.5\text{mA}$
Forward Voltage	$V_F$	—	0.37 0.30	0.45 0.36	V	$I_F = 2.0\text{A}$ , $T_A = +25^\circ\text{C}$ $I_F = 2.0\text{A}$ , $T_A = +125^\circ\text{C}$
Leakage Current (Note 6)	$I_R$	—	40 0.37	250 1.5	$\mu\text{A}$ mA	$V_R = 5\text{V}$ , $T_A = +25^\circ\text{C}$ $V_R = 30\text{V}$ , $T_A = +25^\circ\text{C}$
Total Capacitance	$C_T$	—	40	—	pF	$V_R = 10\text{V}$ , $f = 1.0\text{MHz}$

Notes: 5. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.  
6. Short duration pulse test used to minimize self-heating effect.

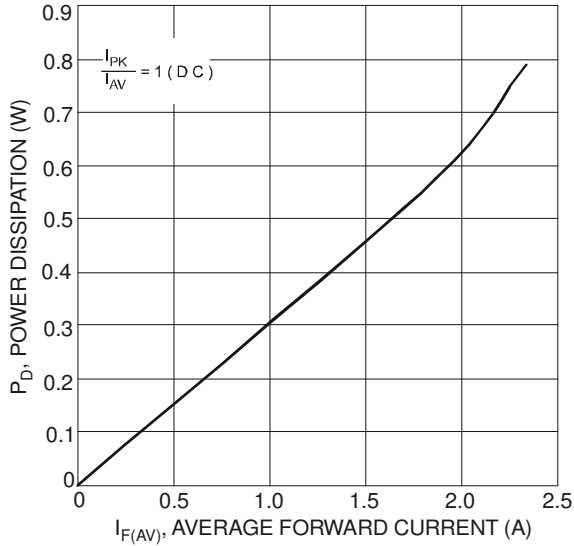


Fig. 1 Forward Power Dissipation

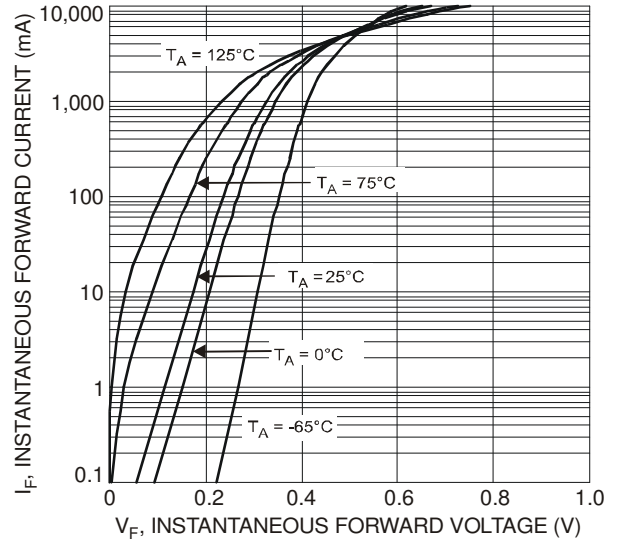


Fig. 2 Typical Forward Characteristics

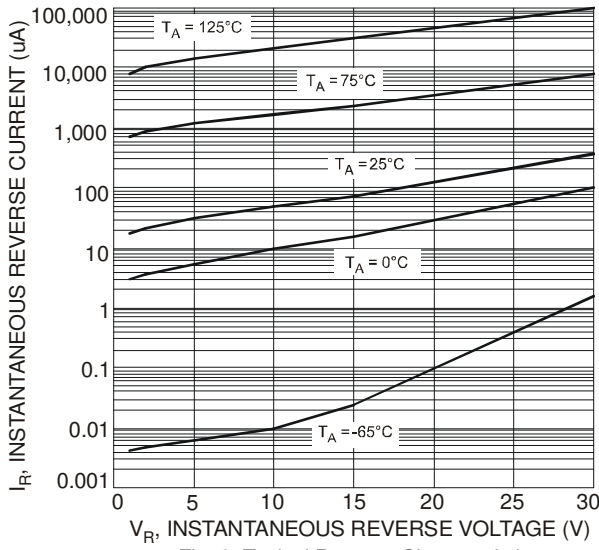


Fig. 3 Typical Reverse Characteristics

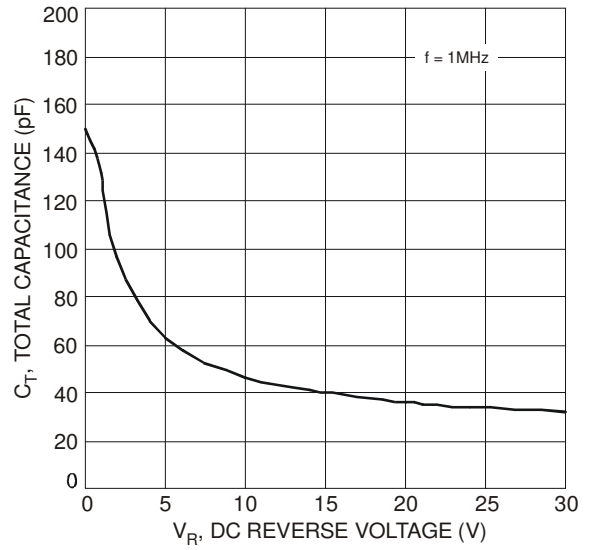


Fig. 4 Total Capacitance vs. Reverse Voltage

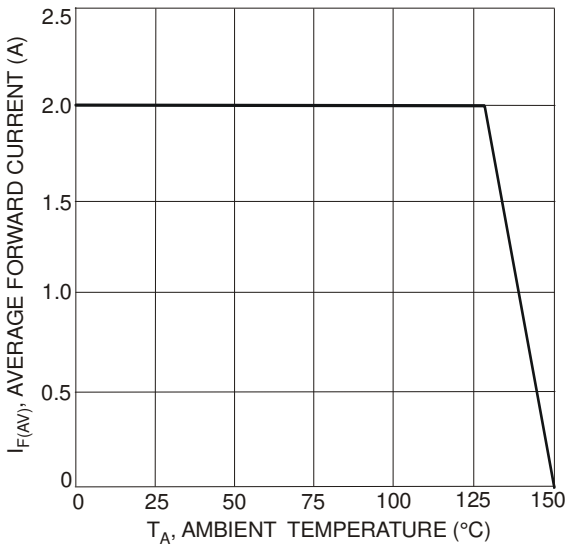


Fig. 5 Forward Current Derating Curve

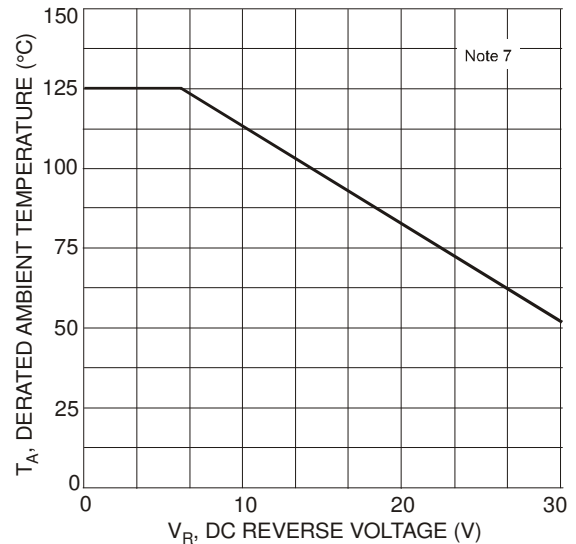
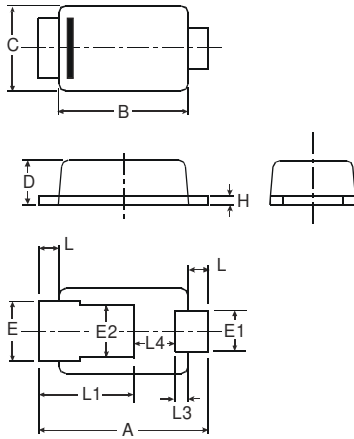


Fig. 6 Operating Temperature Derating

Notes: 7. Polyimide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.

## Package Outline Dimensions

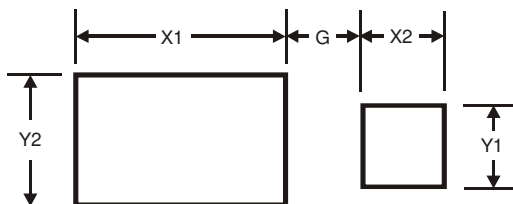
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



POWERDI <sup>®</sup> 323			
Dim	Min	Max	Typ
A	2.40	2.60	2.50
B	1.85	1.95	1.90
C	1.20	1.30	1.25
D	0.60	0.70	0.65
E	0.78	0.98	0.88
E1	0.50	0.70	0.60
E2	0.60	1.00	0.80
H	0.08	0.18	0.13
L	0.20	0.40	0.30
L1	—	—	1.40
L3	—	—	0.20
L4	0.40	0.80	0.60
All Dimensions in mm			

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
G	0.5
X1	2.0
X2	0.8
Y1	0.8
Y2	1.1

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